

ABSTRACT OF THE DISCLOSURE

The present invention relates to a three-dimensional visual inspection method of semiconductor packages and apparatus using single camera, which is able to carry out a three-dimensional visual inspection of small-size, high-density semiconductor packages having a large-scale of integration by using a single camera.

The present invention presents an optical system that can obtain a stereo image to extract distance information by using an LED light and a single camera, and it also presents a three-dimensional measurement/inspection method using the same.